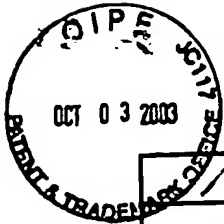


FORM PTO - 1449 INFORMATION DISCLOSURE STATEMENT				ATTORNEY DOCKET NO.: IBX-005 APPLICANT(S): Card et al. SERIAL NO.: 10/621,532 FILING DATE: 7/17/03 GROUP: Not yet assigned				
U.S. PATENT DOCUMENTS								
EXAM. INIT.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE		
TS	A1	5,467,883	11/21/95	Frye et al.	216	60	11/27/93	
TS	A2	5,559,690	9/24/96	Keeler et al.	364 700	164 941	9/16/94	
TS	A3	5,654,903	8/5/97	Reitman et al.	364 702	551.01 81	11/7/95	
TS	A4	5,740,033	4/14/98	Wassick et al.	364 700	140 27	10/13/92	
TS	A5	6,268,226	7/31/01	Angell et al.	438	16	6/30/99	
FOREIGN PATENT DOCUMENTS								
EXAM. INIT.	DOCUMENT NUMBER	DATE	COUNTRY CODE	CLASS	SUB CLASS	FILING DATE	ABSTRACT ONLY	ENGLISH LANG (Y/N)
TS	B1	WO 01/57605	8/9/01	WO	G05B 13/04	1/11/01	N	Y
TS	B2	DE196 37 917 A1	3/19/98	DE	G05B 13/04	9/17/96	Y	
OTHER ART, JOURNAL ARTICLES, ETC.								
EXAM. INIT.	OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication)							
TS	C1	Card et al., "Dynamic Neural Control for Plasma Etch Process," <u>IEEE Transactions on Neural Networks</u> , (1997). p. 1-18						
TS	C2	Dillon et al., "Guest Editorial Everyday Applications of Neural Networks," <u>IEEE Transactions on Neural Networks</u> , 8:4 (July 1997). 825-826						
TS	C3	Hatzipantelis et al., "Comparing Hidden Markov Models with Artificial Neural Network Architectures for Condition Monitoring Applications," <u>Artificial Neural Networks</u> , 26-28, Conference Publication No. 409 (June 1995). p. 1-6						
TS	C4	Kim et al., "Intelligent Control of Via Formation by Photosensitive BCB for MCM-L/D Applications," <u>IEEE Transactions on Semiconductor Manufacturing</u> , 12:503 (1999). p. 1-12						
TS	C5	Konstantopoulos et al., "Controllers with Diagnostic Capabilities. A Neural Network Implementation. Journal of Intelligent and Robotic Systems," Department of Electrical Engineering, University of Notre Dame, IN 12: 197-228 (1995).						



	C6	Lada et al., "A Wavelet-Based Procedure for Process Fault Detection," (September 17, 2001). pg. 1-30
TS	C7	Moyne, "AEC/APC Vision: A Research and Suppliers' Point of View," 3 rd Annual European AEC/APC Conference Proceedings (2002). pg. 1-25
TS	C8	Rietman et al., "A Study on $\mathcal{R}^m \rightarrow \mathcal{R}^1$ Maps: Application to a 0.16- μm Via Etch Process Endpoint," IEEE (2000). pg. 457-468
TS	C9	Rietman et al., "A System Model for Feedback Control and Analysis of Yield: A Multistep Process Model of Effective Gate Length, Poly Line Width, and IV Parameters", IEEE (2001). pg. 32-46
TS	C10	Rietman, "Neural Networks in Plasma Processing," <u>Journal of Vacuum Science and Technology: Part B, IEEE Transactions on Semiconductor Manufacturing</u> , 14:1 (2001). 508-510
TS	C11	Smyth et. al., "Hidden Markov Models an Neural Networks for Fault detection in Dynamic Systems," California Institute of Technology (1993). pg. 582-591
TS	C12	Zhang et al, "Control of Spatial Uniformity in Microelectronics Manufacturing: An Integrated Approach," Proceedings of AEC/APC (2000). pg. 1-38
/Thomas Stevens/ (09/13/2006) EXAMINER		DATE CONSIDERED 09/13/2006